

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Docket No: Q78432
Hien Boon TAN, et al.
Appln. No.: 10/721,382 Group Art Unit: 2822
Confirmation No.: 6007 Examiner: David E. Graybill
Filed: November 26, 2003
For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF MANUFACTURING

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the "Notice of Non-Compliant Amendment," mailed December 27, 2007, submitted herewith is a corrected AMENDMENT TO THE CLAIMS section.

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